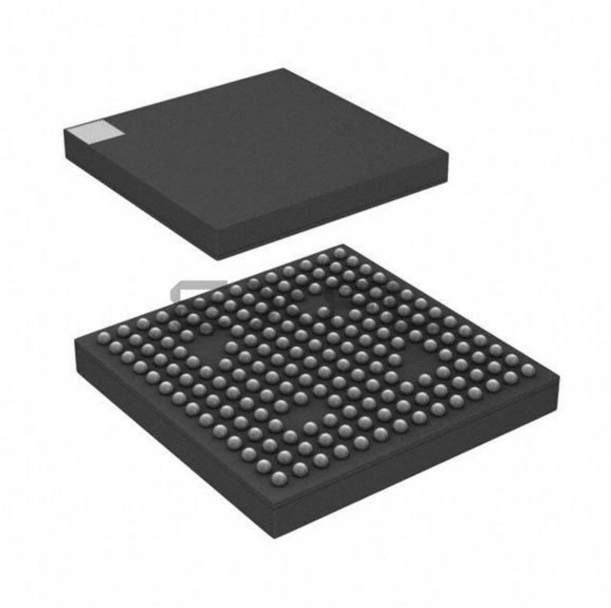

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Blackfin+
Interface	CAN, DSPI, EBI/EMI, I²C, PPI, QSPI, SD/SDIO, SPI, SPORT, UART/USART, USB OTG
Clock Rate	300MHz
Non-Volatile Memory	ROM (512kB)
On-Chip RAM	256kB
Voltage - I/O	1.8V, 3.3V
Voltage - Core	1.10V
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	184-LFBGA, CSPBGA
Supplier Device Package	184-CSPBGA (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/adbf703wcbcz311

TABLE OF CONTENTS

REVISION HISTORY

9/15—Rev. 0 to Rev. A

- A similar buffer that interrupts on fractional buffers (for example, 1/2, 1/4).
- 1D DMA—uses a set of identical ping-pong buffers defined by a linked ring of two-word descriptor sets, each containing a link pointer and an address.
- 1D DMA—uses a linked list of 4 word descriptor sets containing a link pointer, an address, a length, and a configuration.
- 2D DMA—uses an array of one-word descriptor sets, specifying only the base DMA address.
- 2D DMA—uses a linked list of multi-word descriptor sets, specifying everything.

Event Handling

The processor provides event handling that supports both nesting and prioritization. Nesting allows multiple event service routines to be active simultaneously. Prioritization ensures that servicing of a higher-priority event takes precedence over servicing of a lower-priority event. The processor provides support for five different types of events:

- Emulation—An emulation event causes the processor to enter emulation mode, allowing command and control of the processor through the JTAG interface.
- Reset—This event resets the processor.
- Nonmaskable interrupt (NMI)—The NMI event can be generated either by the software watchdog timer, by the $\overline{\text{NMI}}$ input signal to the processor, or by software. The NMI event is frequently used as a power-down indicator to initiate an orderly shutdown of the system.
- Exceptions—Events that occur synchronously to program flow (in other words, the exception is taken before the instruction is allowed to complete). Conditions such as data alignment violations and undefined instructions cause exceptions.
- Interrupts —Events that occur asynchronously to program flow. They are caused by input signals, timers, and other peripherals, as well as by an explicit software instruction.

System Event Controller (SEC)

The SEC manages the enabling, prioritization, and routing of events from each system interrupt or fault source. Additionally, it provides notification and identification of the highest priority active system interrupt request to the core and routes system fault sources to its integrated fault management unit. The SEC triggers core general-purpose interrupt IVG11. It is recommended that IVG11 be set to allow self-nesting. The four lower priority interrupts (IVG15-12) may be used for software interrupts.

Trigger Routing Unit (TRU)

The TRU provides system-level sequence control without core intervention. The TRU maps trigger masters (generators of triggers) to trigger slaves (receivers of triggers). Slave endpoints can be configured to respond to triggers in various ways. Common applications enabled by the TRU include:

- Automatically triggering the start of a DMA sequence after a sequence from another DMA channel completes
- Software triggering
- Synchronization of concurrent activities

General-Purpose I/O (GPIO)

Each general-purpose port pin can be individually controlled by manipulation of the port control, status, and interrupt registers:

- GPIO direction control register—Specifies the direction of each individual GPIO pin as input or output.
- GPIO control and status registers—A write one to modify mechanism allows any combination of individual GPIO pins to be modified in a single instruction, without affecting the level of any other GPIO pins.
- GPIO interrupt mask registers—Allow each individual GPIO pin to function as an interrupt to the processor. GPIO pins defined as inputs can be configured to generate hardware interrupts, while output pins can be triggered by software interrupts.
- GPIO interrupt sensitivity registers—Specify whether individual pins are level- or edge-sensitive and specify—if edge-sensitive—whether just the rising edge or both the rising and falling edges of the signal are significant.

Pin Interrupts

Every port pin on the processor can request interrupts in either an edge-sensitive or a level-sensitive manner with programmable polarity. Interrupt functionality is decoupled from GPIO operation. Three system-level interrupt channels (PINT0–3) are reserved for this purpose. Each of these interrupt channels can manage up to 32 interrupt pins. The assignment from pin to interrupt is not performed on a pin-by-pin basis. Rather, groups of eight pins (half ports) can be flexibly assigned to interrupt channels.

Every pin interrupt channel features a special set of 32-bit memory-mapped registers that enable half-port assignment and interrupt management. This includes masking, identification, and clearing of requests. These registers also enable access to the respective pin states and use of the interrupt latches, regardless of whether the interrupt is masked or not. Most control registers feature multiple MMR address entries to write-one-to-set or write-one-to-clear them individually.

Pin Multiplexing

The processor supports a flexible multiplexing scheme that multiplexes the GPIO pins with various peripherals. A maximum of 4 peripherals plus GPIO functionality is shared by each GPIO pin. All GPIO pins have a bypass path feature—that is, when the

Table 3. Clock Dividers

Clock Source	Divider (if Available on SYS_CLKOUT)
CCLK (Core Clock)	By 16
SYSCLK (System Clock)	By 8
SCLK0 (System Clock, All Peripherals not Covered by SCLK1)	Not available on SYS_CLKOUT
SCLK1 (System Clock for Crypto Engines and MDMA)	By 8
DCLK (LPDDR/DDR2 Clock)	By 8
OCLK (Output Clock)	Programmable
CLKBUF	None, direct from SYS_CLKIN

Power Management

As shown in Table 4, the processor supports multiple power domains, which maximizes flexibility while maintaining compliance with industry standards and conventions. There are no sequencing requirements for the various power domains, but all domains must be powered according to the appropriate Specifications table for processor operating conditions; even if the feature/peripheral is not used.

Table 4. Power Domains

Power Domain	V_{DD} Range
All Internal Logic	V_{DD_INT}
DDR2/LPDDR	V_{DD_DMC}
USB	V_{DD_USB}
OTP Memory	V_{DD_OTP}
HADC	V_{DD_HADC}
RTC	V_{DD_RTC}
All Other I/O (Includes SYS, JTAG, and Ports Pins)	V_{DD_EXT}

The dynamic power management feature of the processor allows the processor's core clock frequency (f_{CCLK}) to be dynamically controlled.

The power dissipated by a processor is largely a function of its clock frequency and the square of the operating voltage. For example, reducing the clock frequency by 25% results in a 25% reduction in dynamic power dissipation.

See Table 5 for a summary of the power settings for each mode.

Full-On Operating Mode—Maximum Performance

In the full-on mode, the PLL is enabled and is not bypassed, providing capability for maximum operational frequency. This is the power-up default execution state in which maximum performance can be achieved. The processor core and all enabled peripherals run at full speed.

Deep Sleep Operating Mode—Maximum Dynamic Power Savings

The deep sleep mode maximizes dynamic power savings by disabling the clocks to the processor core and to all synchronous peripherals. Asynchronous peripherals may still be running but cannot access internal resources or external memory.

Table 5. Power Settings

Mode/State	PLL	PLL Bypassed	f_{CCLK}	f_{SYSCLK}, f_{DCLK}, f_{SCLK0}, f_{SCLK1}	Core Power
Full On	Enabled	No	Enabled	Enabled	On
Deep Sleep	Disabled	—	Disabled	Disabled	On
Hibernate	Disabled	—	Disabled	Disabled	Off

Hibernate State—Maximum Static Power Savings

The hibernate state maximizes static power savings by disabling the voltage and clocks to the processor core and to all of the peripherals. This setting signals the external voltage regulator supplying the VDD_INT pins to shut off using the SYS_EXTWAKE signal, which provides the lowest static power dissipation.

Any critical information stored internally (for example, memory contents, register contents, and other information) must be written to a nonvolatile storage device (or self-refreshed DRAM) prior to removing power if the processor state is to be preserved.

Because the V_{DD_EXT} pins can still be supplied in this mode, all of the external pins three-state, unless otherwise specified. This allows other devices that may be connected to the processor to still have power applied without drawing unwanted current.

Reset Control Unit

Reset is the initial state of the whole processor or the core and is the result of a hardware- or software-triggered event. In this state, all control registers are set to their default values and functional units are idle. Exiting a full system reset starts with the core being ready to boot.

The reset control unit (RCU) controls how all the functional units enter and exit reset. Differences in functional requirements and clocking constraints define how reset signals are generated. Programs must guarantee that none of the reset functions puts the system into an undefined state or causes resources to stall. This is particularly important when the core is reset (programs must ensure that there is no pending system activity involving the core when it is being reset).

From a system perspective, reset is defined by both the reset target and the reset source described as follows in the following list.

ADSP-BF70x DETAILED SIGNAL DESCRIPTIONS

Table 6 provides a detailed description of each pin.

Table 6. ADSP-BF70x Detailed Signal Descriptions

Port Name	Direction	Description
CAN_RX	Input	**Receive.** Typically an external CAN transceiver's RX output.
CAN_TX	Output	**Transmit.** Typically an external CAN transceiver's TX input.
CNT_DG	Input	**Count Down and Gate.** Depending on the mode of operation this input acts either as a count down signal or a gate signal Count Down - This input causes the GP counter to decrement Gate - Stops the GP counter from incrementing or decrementing.
CNT_UD	Input	**Count Up and Direction.** Depending on the mode of operation this input acts either as a count up signal or a direction signal Count Up - This input causes the GP counter to increment Direction - Selects whether the GP counter is incrementing or decrementing.
CNT_ZM	Input	**Count Zero Marker.** Input that connects to the zero marker output of a rotary device or detects the pressing of a pushbutton.
DMC_Ann	Output	**Address n.** Address bus.
DMC_BAn	Output	**Bank Address Input n.** Defines which internal bank an ACTIVATE, READ, WRITE, or PRECHARGE command is being applied to on the dynamic memory. Also defines which mode registers (MR, EMR, EMR2, and/or EMR3) are loaded during the LOAD MODE REGISTER command.
$\overline{\text{DMC\_CAS}}$	Output	**Column Address Strobe.** Defines the operation for external dynamic memory to perform in conjunction with other DMC command signals. Connect to the CAS input of dynamic memory.
DMC_CK	Output	**Clock.** Outputs DCLK to external dynamic memory.
$\overline{\text{DMC\_CK}}$	Output	**Clock (Complement).** Complement of DMC_CK.
DMC_CKE	Output	**Clock enable.** Active high clock enables. Connects to the dynamic memory's CKE input.
$\overline{\text{DMC\_CSn}}$	Output	**Chip Select n.** Commands are recognized by the memory only when this signal is asserted.
DMC_DQnn	I/O	**Data n.** Bidirectional Data bus.
DMC_LDM	Output	**Data Mask for Lower Byte.** Mask for DMC_DQ07:DMC_DQ00 write data when driven high. Sampled on both edges of the data strobe by the dynamic memory.
DMC_LDQS	I/O	**Data Strobe for Lower Byte.** DMC_DQ07:DMC_DQ00 data strobe. Output with Write Data. Input with Read Data. May be single-ended or differential depending on register settings.
$\overline{\text{DMC\_LDQS}}$	I/O	**Data Strobe for Lower Byte (complement).** Complement of LDQS. Not used in single-ended mode.
DMC_ODT	Output	**On-die termination.** Enables dynamic memory termination resistances when driven high (assuming the memory is properly configured). ODT is enabled/disabled regardless of read or write commands.
$\overline{\text{DMC\_RAS}}$	Output	**Row Address Strobe.** Defines the operation for external dynamic memory to perform in conjunction with other DMC command signals. Connect to the RAS input of dynamic memory.
DMC_UDM	Output	**Data Mask for Upper Byte.** Mask for DMC_DQ15:DMC_DQ08 write data when driven high. Sampled on both edges of the data strobe by the dynamic memory.
DMC_UDQS	I/O	**Data Strobe for Upper Byte.** DMC_DQ15:DMC_DQ08 data strobe. Output with Write Data. Input with Read Data. May be single-ended or differential depending on register settings.
$\overline{\text{DMC\_UDQS}}$	I/O	**Data Strobe for Upper Byte (complement).** Complement of UDQSb. Not used in single-ended mode.
DMC_VREF	Input	**Voltage Reference.** Connect to half of the VDD_DMC voltage.
$\overline{\text{DMC\_WE}}$	Output	**Write Enable.** Defines the operation for external dynamic memory to perform in conjunction with other DMC command signals. Connect to the $\overline{\text{WE}}$ input of dynamic memory.
PPI_CLK	I/O	**Clock.** Input in external clock mode, output in internal clock mode.
PPI_Dnn	I/O	**Data n.** Bidirectional data bus.
PPI_FS1	I/O	**Frame Sync 1 (HSYNC).** Behavior depends on EPPI mode. See the EPPI HRM chapter for more details.
PPI_FS2	I/O	**Frame Sync 2 (VSYNC).** Behavior depends on EPPI mode. See the EPPI HRM chapter for more details.
PPI_FS3	I/O	**Frame Sync 3 (FIELD).** Behavior depends on EPPI mode. See the EPPI HRM chapter for more details.
HADC_VINn	Input	**Analog Input at channel n.** Analog voltage inputs for digital conversion.

Table 6. ADSP-BF70x Detailed Signal Descriptions (Continued)

Port Name	Direction	Description
SPT_BCLK	I/O	**Channel B Clock.** Data and Frame Sync are driven/sampled with respect to this clock. This signal can be either internally or externally generated.
SPT_BD0	I/O	**Channel B Data 0.** Primary bidirectional data I/O. This signal can be configured as an output to transmit serial data, or as an input to receive serial data.
SPT_BD1	I/O	**Channel B Data 1.** Secondary bidirectional data I/O. This signal can be configured as an output to transmit serial data, or as an input to receive serial data.
SPT_BFS	I/O	**Channel B Frame Sync.** The frame sync pulse initiates shifting of serial data. This signal is either generated internally or externally.
SPT_BTDV	Output	**Channel B Transmit Data Valid.** This signal is optional and only active when SPORT is configured in multi-channel transmit mode. It is asserted during enabled slots.
SYS_BMODEn	Input	**Boot Mode Control n.** Selects the boot mode of the processor.
SYS_CLKIN	Input	**Clock/Crystal Input.** Connect to an external clock source or crystal.
SYS_CLKOUT	Output	**Processor Clock Output.** Outputs internal clocks. Clocks may be divided down. See the CGU chapter of the HRM for more details.
SYS_EXTWAKE	Output	**External Wake Control.** Drives low during hibernate and high all other times. Typically connected to the enable input of the voltage regulator controlling the VDD_INT supply.
$\overline{\text{SYS\_FAULT}}$	I/O	**Active-Low Fault Output.** Indicates internal faults or senses external faults depending on the operating mode.
$\overline{\text{SYS\_HWRST}}$	Input	**Processor Hardware Reset Control.** Resets the device when asserted.
$\overline{\text{SYS\_NMI}}$	Input	**Non-maskable Interrupt.** See the processor hardware and programming references for more details.
$\overline{\text{SYS\_RESOUT}}$	Output	**Reset Output.** Indicates that the device is in the reset or hibernate state.
SYS_WAKEn	Input	**Power Saving Mode Wakeup n.** Wake-up source input for deep sleep and/or hibernate mode.
SYS_XTAL	Output	**Crystal Output.** Drives an external crystal. Must be left unconnected if an external clock is driving CLKIN.
JTG_SWCLK	I/O	**Serial Wire Clock.** Clocks data into and out of the target during debug.
JTG_SWDIO	I/O	**Serial Wire DIO.** Sends and receives serial data to and from the target during debug.
JTG_SWO	Output	**Serial Wire Out.** Provides trace data to the emulator.
JTG_TCK	Input	**JTAG Clock.** JTAG test access port clock.
JTG_TDI	Input	**JTAG Serial Data In.** JTAG test access port data input.
JTG_TDO	Output	**JTAG Serial Data Out.** JTAG test access port data output.
JTG_TMS	Input	**JTAG Mode Select.** JTAG test access port mode select.
$\overline{\text{JTG\_TRST}}$	Input	**JTAG Reset.** JTAG test access port reset.
TM_ACIn	Input	**Alternate Capture Input n.** Provides an additional input for WIDCAP, WATCHDOG, and PININT modes.
TM_ACLKn	Input	**Alternate Clock n.** Provides an additional time base for use by an individual timer.
TM_CLK	Input	**Clock.** Provides an additional global time base for use by all the GP timers.
TM_TMRn	I/O	**Timer n.** The main input/output signal for each timer.
TRACE_CLK	Output	**Trace Clock.** Clock output.
TRACE_Dnn	Output	**Trace Data n.** Unidirectional data bus.
TWI_SCL	I/O	**Serial Clock.** Clock output when master, clock input when slave.
TWI_SDA	I/O	**Serial Data.** Receives or transmits data.
$\overline{\text{UART\_CTS}}$	Input	**Clear to Send.** Flow control signal.
$\overline{\text{UART\_RTS}}$	Output	**Request to Send.** Flow control signal.
$\overline{\text{UART\_RX}}$	Input	**Receive.** Receive input. Typically connects to a transceiver that meets the electrical requirements of the device being communicated with.
$\overline{\text{UART\_TX}}$	Output	**Transmit.** Transmit output. Typically connects to a transceiver that meets the electrical requirements of the device being communicated with.
USB_CLKIN	Input	**Clock/Crystal Input.** This clock input is multiplied by a PLL to form the USB clock. See data sheet specifications for frequency/tolerance information.

Table 10. Signal Multiplexing for Port C

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PC_00	UART1_TX	SPT0_AD1	PPI0_D15		
PC_01	UART1_RX	SPT0_BD1	PPI0_D14	SMC0_A09	TM0_ACI4
PC_02	UART0_RTS	CAN0_RX	PPI0_D13	SMC0_A10	TM0_ACI5/SYS_ WAKE3
PC_03	UART0_CTS	CAN0_TX	PPI0_D12	SMC0_A11	TM0_ACI0
PC_04	SPT0_BCLK	SPI0_CLK	MSI0_D1	SMC0_A12	TM0_ACLK0
PC_05	SPT0_AFS	TM0_TMR3	MSI0_CMD		
PC_06	SPT0_BD0	SPI0_MISO	MSI0_D3		
PC_07	SPT0_BFS	SPI0_MOSI	MSI0_D2		TM0_ACI2
PC_08	SPT0_AD0	SPI0_D2	MSI0_D0		
PC_09	SPT0_ACLK	SPI0_D3	MSI0_CLK		TM0_ACLK2
PC_10	SPT1_BCLK	MSI0_D4	SPI1_SEL3		TM0_ACLK1
PC_11	SPT1_BFS	MSI0_D5	SPI0_SEL3		
PC_12	SPT1_BD0	MSI0_D6			
PC_13	SPT1_BD1	MSI0_D7			
PC_14	SPT1_BTDV	MSI0_INT			

Table 11. ADSP-BF70x 12 mm × 12 mm 88-Lead LFCSP (QFN) Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
SPT0_AFS	SPORT0 Channel A Frame Sync	A	PA_12
SPT0_AFS	SPORT0 Channel A Frame Sync	C	PC_05
SPT0_ATDV	SPORT0 Channel A Transmit Data Valid	A	PA_15
SPT0_BCLK	SPORT0 Channel B Clock	B	PB_04
SPT0_BCLK	SPORT0 Channel B Clock	C	PC_04
SPT0_BD0	SPORT0 Channel B Data 0	B	PB_05
SPT0_BD0	SPORT0 Channel B Data 0	C	PC_06
SPT0_BD1	SPORT0 Channel B Data 1	B	PB_07
SPT0_BD1	SPORT0 Channel B Data 1	C	PC_01
SPT0_BFS	SPORT0 Channel B Frame Sync	B	PB_06
SPT0_BFS	SPORT0 Channel B Frame Sync	C	PC_07
SPT0_BTDV	SPORT0 Channel B Transmit Data Valid	A	PA_15
SPT1_ACLK	SPORT1 Channel A Clock	A	PA_08
SPT1_AD0	SPORT1 Channel A Data 0	A	PA_10
SPT1_AD1	SPORT1 Channel A Data 1	A	PA_11
SPT1_AFS	SPORT1 Channel A Frame Sync	A	PA_09
SPT1_ATDV	SPORT1 Channel A Transmit Data Valid	A	PA_07
SPT1_BCLK	SPORT1 Channel B Clock	B	PB_00
SPT1_BCLK	SPORT1 Channel B Clock	C	PC_10
SPT1_BD0	SPORT1 Channel B Data 0	B	PB_02
SPT1_BD1	SPORT1 Channel B Data 1	B	PB_03
SPT1_BFS	SPORT1 Channel B Frame Sync	B	PB_01
SPT1_BTDV	SPORT1 Channel B Transmit Data Valid	A	PA_07
SYS_BMODE0	Boot Mode Control 0	Not Muxed	SYS_BMODE0
SYS_BMODE1	Boot Mode Control 1	Not Muxed	SYS_BMODE1
SYS_CLKIN	Clock/Crystal Input	Not Muxed	SYS_CLKIN
SYS_CLKOUT	Processor Clock Output	Not Muxed	SYS_CLKOUT
SYS_EXTWAKE	External Wake Control	Not Muxed	SYS_EXTWAKE
$\overline{\text{SYS\_FAULT}}$	Active-Low Fault Output	Not Muxed	$\overline{\text{SYS\_FAULT}}$
$\overline{\text{SYS\_HWRST}}$	Processor Hardware Reset Control	Not Muxed	$\overline{\text{SYS\_HWRST}}$
$\overline{\text{SYS\_NMI}}$	Non-maskable Interrupt	Not Muxed	$\overline{\text{SYS\_NMI}}$
$\overline{\text{SYS\_RESOUT}}$	Reset Output	Not Muxed	$\overline{\text{SYS\_RESOUT}}$
SYS_WAKE0	Power Saving Mode Wake-up 0	B	PB_07
SYS_WAKE1	Power Saving Mode Wake-up 1	B	PB_08
SYS_WAKE2	Power Saving Mode Wake-up 2	B	PB_12
SYS_WAKE3	Power Saving Mode Wake-up 3	C	PC_02
SYS_WAKE4	Power Saving Mode Wake-up 4	A	PA_12
SYS_XTAL	Crystal Output	Not Muxed	SYS_XTAL
TM0_ACI0	TIMER0 Alternate Capture Input 0	C	PC_03
TM0_ACI1	TIMER0 Alternate Capture Input 1	B	PB_01
TM0_ACI2	TIMER0 Alternate Capture Input 2	C	PC_07
TM0_ACI3	TIMER0 Alternate Capture Input 3	B	PB_09
TM0_ACI4	TIMER0 Alternate Capture Input 4	C	PC_01
TM0_ACI5	TIMER0 Alternate Capture Input 5	C	PC_02
TM0_ACI6	TIMER0 Alternate Capture Input 6	A	PA_12
TM0_ACLK0	TIMER0 Alternate Clock 0	C	PC_04

ADSP-BF70x DESIGNER QUICK REFERENCE

Table 15 provides a quick reference summary of pin related information for circuit board design. The columns in this table provide the following information:

- Signal Name: The Signal Name column in the table includes the signal name for every pin and (where applicable) the GPIO multiplexed pin function for every pin.
- Pin Type: The Type column in the table identifies the I/O type or supply type of the pin. The abbreviations used in this column are na (none), I/O (input/output), a (analog), s (supply), and g (ground).
- Driver Type: The Driver Type column in the table identifies the driver type used by the pin. The driver types are defined in the output drive currents section of this data sheet.
- Internal Termination: The Int Term column in the table specifies the termination present when the processor is not in the reset or hibernate state. The abbreviations used in this column are wk (weak keeper, weakly retains previous value driven on the pin), pu (pull-up), or pd (pull-down).
- Reset Termination: The Reset Term column in the table specifies the termination present when the processor is in the reset state. The abbreviations used in this column are wk (weak keeper, weakly retains previous value driven on the pin), pu (pull-up), or pd (pull-down).
- Reset Drive: The Reset Drive column in the table specifies the active drive on the signal when the processor is in the reset state.
- Hibernate Termination: The Hiber Term column in the table specifies the termination present when the processor is in the hibernate state. The abbreviations used in this column are wk (weak keeper, weakly retains previous value driven on the pin), pu (pull-up), or pd (pull-down).
- Hibernate Drive: The Hiber Drive column in the table specifies the active drive on the signal when the processor is in the hibernate state.
- Power Domain: The Power Domain column in the table specifies the power supply domain in which the signal resides.
- Description and Notes: The Description and Notes column in the table identifies any special requirements or characteristics for the signal. If no special requirements are listed the signal may be left unconnected if it is not used. Also, for multiplexed general-purpose I/O pins, this column identifies the functions available on the pin.

If an external pull-up or pull-down resistor is required for any signal, 100 kΩ is the maximum value that can be used unless otherwise noted.

Note that for Port A, Port B, and Port C (PA_00 to PC_14), when SYS_HWRST is low, these pads are three-state. After SYS_HWRST is released, but before code execution begins, these pins are internally pulled up. Subsequently, the state depends on the input enable and output enable which are controlled by software.

Software control of internal pull-ups works according to the following settings in the PADS_PCFG0 register. When PADS_PCFG0 = 0: For PA_15:PA_00, PB_15:PB_00, and PC_14:PC_00, the internal pull-up is enabled when both the input enable and output enable of a particular pin are deasserted. When PADS_PCFG0 = 1: For PA_15:PA_00, PB_15:PB_00, and PC_14:PC_00, the internal pull-up is enabled as long as the output enable of a particular pin is deasserted.

There are some exceptions to this scheme:

- Internal pull-ups are always disabled if MSI mode is selected for that signal.
- The following signals enabled the internal pull-down when the output enable is de-asserted: SMC0_AMS[1:0], SMC0_ARE, SMC0_AWE, SMC0_AOE, SMC0_ARDY, SPI0_SEL[6:1], SPI1_SEL[4:1], and SPI2_SEL[3:1].

Table 15. ADSP-BF70x Designer Quick Reference

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Hiber Term	Hiber Drive	Power Domain	Description and Notes
DMC0_A00	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 0 Notes: No notes.
DMC0_A01	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 1 Notes: No notes.
DMC0_A02	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 2 Notes: No notes.
DMC0_A03	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 3 Notes: No notes.
DMC0_A04	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 4 Notes: No notes.
DMC0_A05	I/O	B	none	none	none	none	none	VDD_DMC	Desc: DMC0 Address 5 Notes: No notes.

Table 18. Peripheral Clock Operating Conditions

Parameter		Restriction	Min	Typ	Max	Unit
f_{OCLK}	Output Clock Frequency				50	MHz
$f_{SYS\_CLKOUTJ}$	SYS_CLKOUT Period Jitter[1, 2]			±2		%
$f_{PCLKPROG}$	Programmed PPI Clock When Transmitting Data and Frame Sync				50	MHz
$f_{PCLKPROG}$	Programmed PPI Clock When Receiving Data or Frame Sync				50	MHz
$f_{PCLKEXT}$	External PPI Clock When Receiving Data and Frame Sync[3, 4]	$f_{PCLKEXT} \leq f_{SCLK0}$			50	MHz
$f_{PCLKEXT}$	External PPI Clock Transmitting Data or Frame Sync[3, 4]	$f_{PCLKEXT} \leq f_{SCLK0}$			50	MHz
$f_{SPTCLKPROG}$	Programmed SPT Clock When Transmitting Data and Frame Sync				50	MHz
$f_{SPTCLKPROG}$	Programmed SPT Clock When Receiving Data or Frame Sync				50	MHz
$f_{SPTCLKEXT}$	External SPT Clock When Receiving Data and Frame Sync[3, 4]	$f_{SPTCLKEXT} \leq f_{SCLK0}$			50	MHz
$f_{SPTCLKEXT}$	External SPT Clock Transmitting Data or Frame Sync[3, 4]	$f_{SPTCLKEXT} \leq f_{SCLK0}$			50	MHz
$f_{SPICLKPROG}$	Programmed SPI Clock When Transmitting Data				50	MHz
$f_{SPICLKPROG}$	Programmed SPI Clock When Receiving Data				50	MHz
$f_{SPICLKEXT}$	External SPI Clock When Receiving Data[3, 4]	$f_{SPICLKEXT} \leq f_{SCLK0}$			50	MHz
$f_{SPICLKEXT}$	External SPI Clock When Transmitting Data[3, 4]	$f_{SPICLKEXT} \leq f_{SCLK0}$			50	MHz
$f_{MSICLKPROG}$	Programmed MSI Clock				50	MHz

[1] SYS_CLKOUT jitter is dependent on the application system design including pin switching activity, board layout, and the jitter characteristics of the SYS_CLKIN source. Due to the dependency on these factors the measured jitter may be higher or lower than this typical specification for each end application.
[2] The value in the Typ field is the percentage of the SYS_CLKOUT period.
[3] The maximum achievable frequency for any peripheral in external clock mode is dependent on being able to meet the setup and hold times in the ac timing specifications section for that peripheral. Pay particular attention to setup and hold times for VDD_EXT = 1.8 V which may preclude the maximum frequency listed here.
[4] The peripheral external clock frequency must also be less than or equal to the f_{SCLK} that clocks the peripheral.

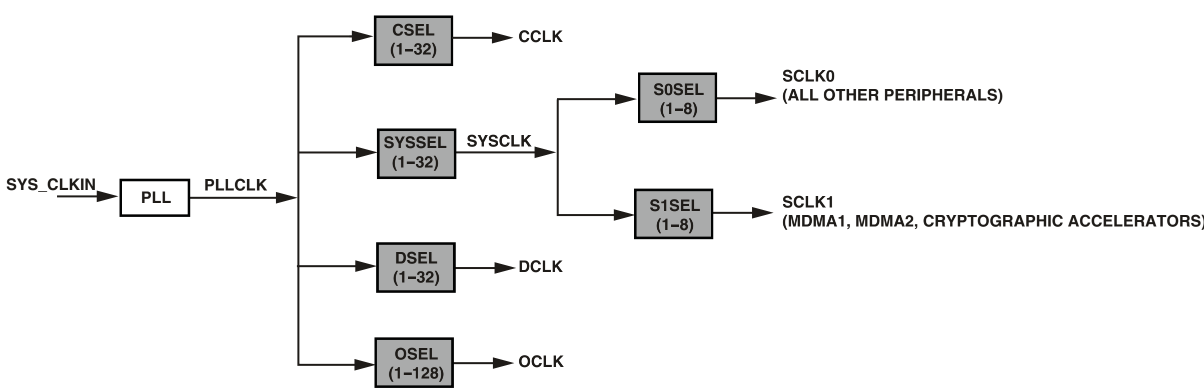

Figure 6. Clock Relationships and Divider Values

Table 19. Phase-Locked Loop Operating Conditions

Parameter		Min	Max	Unit
f_{PLLCLK}	PLL Clock Frequency	230.2	800	MHz
CGU_CTL.MSEL[1]	PLL Multiplier	8	41	

[1] The CGU_CTL.MSEL setting must also be chosen to ensure that the f_{PLLCLK} specification is not violated.

Power-Up Reset Timing

A power-up reset is required to place the processor in a known state after power-up. A power-up reset is initiated by asserting $\overline{SYS\_HWRST}$ and $\overline{JTG\_TRST}$. During power-up reset, all pins are high impedance except for those noted in the ADSP-BF70x Designer Quick Reference on Page 38.

Both $\overline{JTG\_TRST}$ and $\overline{SYS\_HWRST}$ need to be asserted upon power-up, but only $\overline{SYS\_HWRST}$ needs to be released for the device to boot properly. $\overline{JTG\_TRST}$ may be asserted indefinitely for normal operation. $\overline{JTG\_TRST}$ only needs to be released when using an emulator to connect to the DAP for debug or boundary scan. There is an internal pull-down on $\overline{JTG\_TRST}$ to ensure internal emulation logic will always be properly initialized during power-up reset.

Table 30 and Figure 9 show the relationship between power supply startup and processor reset timing, related to the clock generation unit (CGU) and reset control unit (RCU). In Figure 9, $V_{DD\_SUPPLIES}$ are V_{DD_INT}, V_{DD_EXT}, V_{DD_DMC}, V_{DD_USB}, V_{DD_RTC}, V_{DD_OTP}, and V_{DD_HADC}.

There is no power supply sequencing requirement for the ADSP-BF70x processor. However, if saving power during power-on is important, bringing up V_{DD_INT} last is recommended. This avoids a small current drain in the V_{DD_INT} domain during the transition period of I/O voltages from 0 V to within the voltage specification.

Table 30. Power-Up Reset Timing

Parameter		Min	Max	Unit
Timing Requirement				
$t_{RST\_IN\_PWR}$	$\overline{SYS\_HWRST}$ and $\overline{JTG\_TRST}$ Deasserted After V_{DD_INT}, V_{DD_DMC}, V_{DD_USB}, V_{DD_RTC}, V_{DD_OTP}, V_{DD_HADC}, and SYS_CLKIN are Stable and Within Specification	$11 \times t_{CKIN}$		ns
t_{VDDEXT_RST}	$\overline{SYS\_HWRST}$ Deasserted After V_{DD_EXT} is Stable and Within Specifications (No External Pull-Down on $\overline{JTG\_TRST}$)	10		µs
t_{VDDEXT_RST}	$\overline{SYS\_HWRST}$ Deasserted After V_{DD_EXT} is Stable and Within Specifications (10k External Pull-Down on $\overline{JTG\_TRST}$)	1		µs

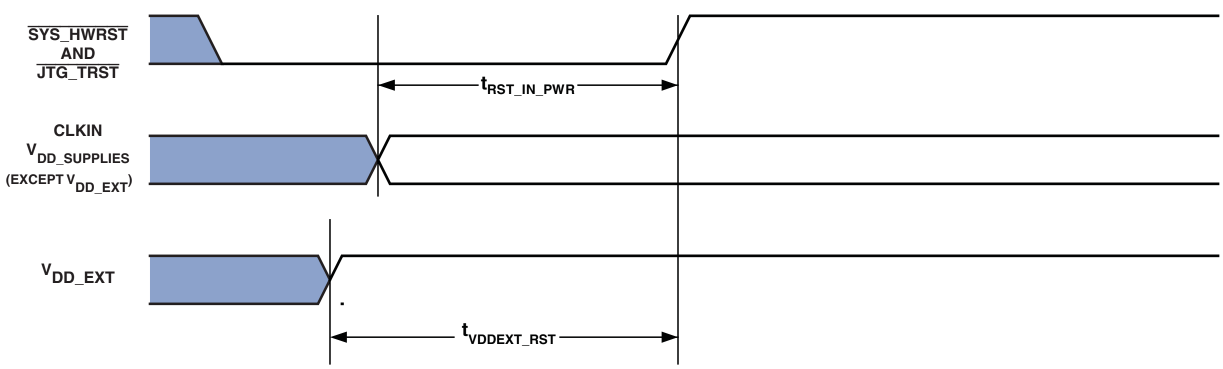

Figure 9. Power-Up Reset Timing

DDR2 SDRAM Clock and Control Cycle Timing

Table 39 and Figure 17 show DDR2 SDRAM clock and control cycle timing, related to the dynamic memory controller (DMC).

Table 39. DDR2 SDRAM Read Cycle Timing, V_{DD_DMC} Nominal 1.8 V

Parameter		200 MHz Min	200 MHz Max	Unit
Switching Characteristics				
t_{CK}	Clock Cycle Time (CL = 2 Not Supported)	5		ns
t_{CH}	High Clock Pulse Width	0.45	0.55	t_{CK}
t_{CL}	Low Clock Pulse Width	0.45	0.55	t_{CK}
t_{IS}	Control/Address Setup Relative to DMC0_CK Rise	350		ps
t_{IH}	Control/Address Hold Relative to DMC0_CK Rise	475		ps

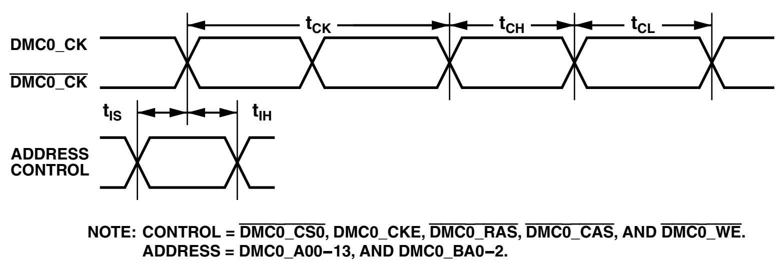

Figure 17. DDR2 SDRAM Clock and Control Cycle Timing

General-Purpose I/O Port Timing (GPIO)

Table 45 and Figure 23 describe I/O timing, related to the general-purpose ports (PORT).

Table 45. General-Purpose I/O Port Timing

Parameter		V_{DD_EXT} 1.8 V/3.3 V Nominal Min	Max	Unit
Timing Requirement				
t_{WFI}	General-Purpose Port Pin Input Pulse Width	$2 \times t_{SCLK0} - 1.5$		ns

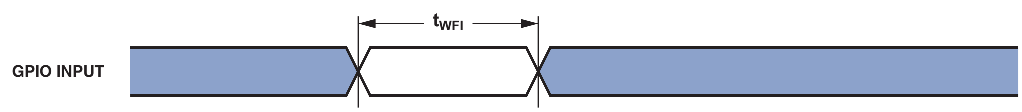

Figure 23. General-Purpose I/O Port Timing

Timer Cycle Timing

Table 46 and Figure 24 describe timer expired operations, related to the general-purpose timer (TIMER). The input signal is asynchronous in width capture mode and external clock mode and has an ideal maximum input frequency of (f_{SCLK0}/4) MHz. The Period Value (VALUE) is the timer period assigned in the TMx_TMRn_PER register and can range from 2 to $2^{32} - 1$.

Table 46. Timer Cycle Timing

Parameter		V_{DD_EXT} 1.8 V Nominal Min	Max	V_{DD_EXT} 3.3 V Nominal Min	Max	Unit
Timing Requirements						
t_{WL}	Timer Pulse Width Input Low[1]	$2 \times t_{SCLK0} - 1.5$		$2 \times t_{SCLK0} - 1.5$		ns
t_{WH}	Timer Pulse Width Input High[1]	$2 \times t_{SCLK0} - 1.5$		$2 \times t_{SCLK0} - 1.5$		ns
Switching Characteristic						
t_{HTO}	Timer Pulse Width Output	$t_{SCLK0} \times \text{VALUE} - 1$		$t_{SCLK0} \times \text{VALUE} - 1$		ns

[1] This specification indicates the minimum instantaneous width that can be tolerated due to duty cycle variation or jitter for TMx signals in width capture and external clock modes. The ideal maximum frequency for TMx signals is listed in Timer Cycle Timing on this page.

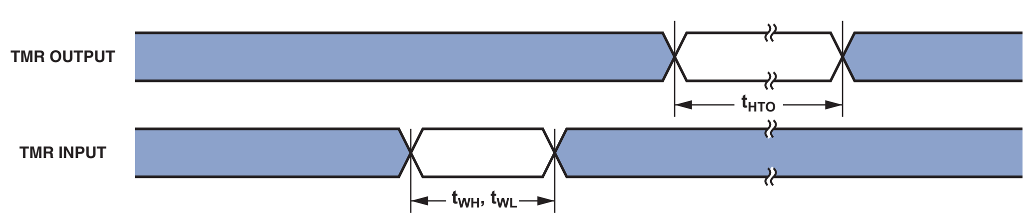

Figure 24. Timer Cycle Timing

Table 50. Serial Ports—Internal Clock

Parameter		V_{DD_EXT} 1.8 V Nominal Min	Max	V_{DD_EXT} 3.3 V Nominal Min	Max	Unit
Timing Requirements						
t_{SFSI}	Frame Sync Setup Before SPT_CLK (Externally Generated Frame Sync in Either Transmit or Receive Mode)[1]	17		14.5		ns
t_{HFSI}	Frame Sync Hold After SPT_CLK (Externally Generated Frame Sync in Either Transmit or Receive Mode)[1]	–0.5		–0.5		ns
t_{SDRI}	Receive Data Setup Before SPT_CLK[1]	6.5		5		ns
t_{HDRI}	Receive Data Hold After SPT_CLK[1]	1.5		1		ns
Switching Characteristics						
t_{DFSI}	Frame Sync Delay After SPT_CLK (Internally Generated Frame Sync in Transmit or Receive Mode)[2]		2		2	ns
t_{HOFSI}	Frame Sync Hold After SPT_CLK (Internally Generated Frame Sync in Transmit or Receive Mode)[2]	–4.5		–3.5		ns
t_{DDTI}	Transmit Data Delay After SPT_CLK[2]		2		2	ns
t_{HDTI}	Transmit Data Hold After SPT_CLK[2]	–5		–3.5		ns
t_{SCLKIW}	SPT_CLK Width[3]	$0.5 \times t_{SPTCLKPROG} - 1.5$		$0.5 \times t_{SPTCLKPROG} - 1.5$		ns
$t_{SPTCLKI}$	SPT_CLK Period[3]	$t_{SPTCLKPROG} - 1.5$		$t_{SPTCLKPROG} - 1.5$		ns

[1] Referenced to the sample edge.
[2] Referenced to drive edge.
[3] See Table 18 on Page 52 in Clock Related Operating Conditions for details on the minimum period that may be programmed for $t_{SPTCLKPROG}$.

Table 51. Serial Ports—Enable and Three-State

Parameter		V_{DD_EXT} 1.8 V Nominal Min	V_{DD_EXT} 1.8 V Nominal Max	V_{DD_EXT} 3.3 V Nominal Min	V_{DD_EXT} 3.3 V Nominal Max	Unit
Switching Characteristics						
t_{DDTEN}	Data Enable from External Transmit SPT_CLK[1]	1		1		ns
t_{DDTTE}	Data Disable from External Transmit SPT_CLK[1]		14		14	ns
t_{DDTIN}	Data Enable from Internal Transmit SPT_CLK[1]	–1.12		–1		ns
t_{DDTTI}	Data Disable from Internal Transmit SPT_CLK[1]		2.8		2.8	ns

[1] Referenced to drive edge.

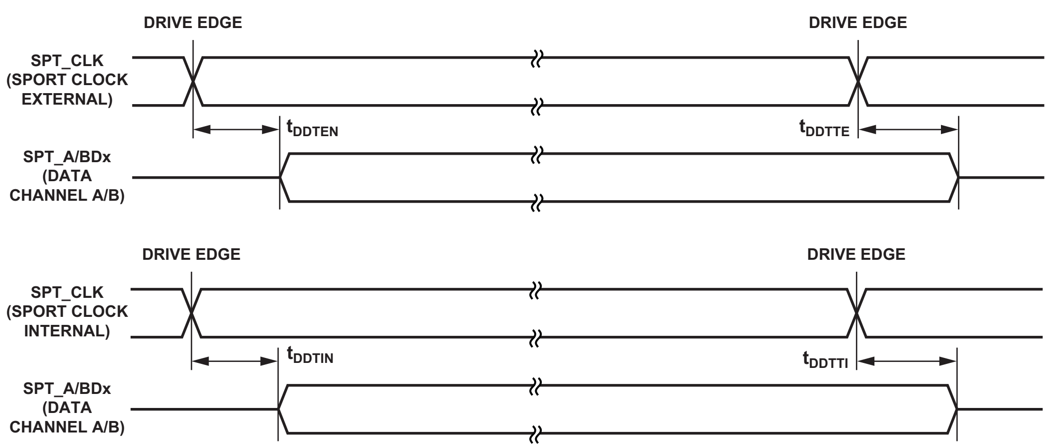

Figure 28. Serial Ports—Enable and Three-State

Serial Peripheral Interface (SPI) Port—Master Timing

Table 54 and Figure 31 describe serial peripheral interface (SPI) port master operations.

When internally generated, the programmed SPI clock ($f_{SPICLKPROG}$) frequency in MHz is set by the following equation where BAUD is a field in the SPI_CLK register that can be set from 0 to 65,535:

$$f_{SPICLKPROG} = \frac{f_{SCLK0}}{(BAUD + 1)}$$

$$t_{SPICLKPROG} = \frac{1}{f_{SPICLKPROG}}$$

Note that:

- In dual mode data transmit, the SPI_MISO signal is also an output.
- In quad mode data transmit, the SPI_MISO, SPI_D2, and SPI_D3 signals are also outputs.
- In dual mode data receive, the SPI_MOSI signal is also an input.
- In quad mode data receive, the SPI_MOSI, SPI_D2, and SPI_D3 signals are also inputs.
- To add additional frame delays, see the documentation for the SPI_DLY register in the hardware reference manual.

Table 54. Serial Peripheral Interface (SPI) Port—Master Timing

Parameter		V_{DD_EXT} 1.8 V Nominal Min	Max	V_{DD_EXT} 3.3 V Nominal Min	Max	Unit
Timing Requirements						
t_{SSPIDM}	Data Input Valid to SPI_CLK Edge (Data Input Setup)	6.5		5.5		ns
t_{HSPIDM}	SPI_CLK Sampling Edge to Data Input Invalid	1		1		ns
Switching Characteristics						
t_{SDSCIM}	$\overline{\text{SPI\_SEL}}$ low to First SPI_CLK Edge	$0.5 \times t_{SCLK0} - 2.5$		$0.5 \times t_{SCLK0} - 1.5$		ns
t_{SPICHM}	SPI_CLK High Period[1]	$0.5 \times t_{SPICLKPROG} - 1.5$		$0.5 \times t_{SPICLKPROG} - 1.5$		ns
t_{SPICLM}	SPI_CLK Low Period[1]	$0.5 \times t_{SPICLKPROG} - 1.5$		$0.5 \times t_{SPICLKPROG} - 1.5$		ns
t_{SPICLK}	SPI_CLK Period[1]	$t_{SPICLKPROG} - 1.5$		$t_{SPICLKPROG} - 1.5$		ns
t_{HDSM}	Last SPI_CLK Edge to $\overline{\text{SPI\_SEL}}$ High	$(0.5 \times t_{SCLK0}) - 2.5$		$(0.5 \times t_{SCLK0}) - 1.5$		ns
t_{SPITDM}	Sequential Transfer Delay[2]	$(STOP \times t_{SPICLK}) - 1.5$		$(STOP \times t_{SPICLK}) - 1.5$		ns
$t_{DDSPIDM}$	SPI_CLK Edge to Data Out Valid (Data Out Delay)		2.5		2	ns
$t_{HDSPIDM}$	SPI_CLK Edge to Data Out Invalid (Data Out Hold)	−4.5		−3.5		ns

[1] See Table 18 on Page 52 in Clock Related Operating Conditions for details on the minimum period that may be programmed for $t_{SPICLKPROG}$.
[2] STOP value set using the SPI_DLY.STOP bits.

Table 67. 184-Ball CSP_BGA Ball Assignment (Numerical by Ball Number)

Ball No.	Signal Name	Ball No.	Signal Name	Ball No.	Signal Name	Ball No.	Signal Name
A01	GND	D08	VDD_DMC	H03	SYS_CLKOUT	L14	GND
A02	DMC0_A09	D09	VDD_DMC	H04	VDD_INT	M01	PC_00
A03	DMC0_BA0	D12	PA_08	H05	GND	M02	RTC0_CLKIN
A04	DMC0_BA1	D13	DMC0_DQ06	H06	GND	M03	PB_15
A05	DMC0_BA2	D14	DMC0_DQ05	H07	GND	M04	PB_12
A06	DMC0_CAS	E01	DMC0_A06	H08	GND	M05	PC_12
A07	DMC0_RAS	E02	DMC0_A05	H09	GND	M06	USB0_VBUS
A08	DMC0_A13	E03	JTG_TDI	H10	GND	M07	USB0_VBC
A09	PA_03	E05	VDD_INT	H11	VDD_DMC	M08	PB_09
A10	DMC0_CK	E06	VDD_DMC	H12	PA_10	M09	PB_05
A11	DMC0_CK	E07	VDD_DMC	H13	PA_11	M10	PB_04
A12	DMC0_LDQS	E08	VDD_DMC	H14	DMC0_UDQS	M11	PB_01
A13	DMC0_LDQS	E09	VDD_DMC	J01	PC_05	M12	PB_03
A14	GND	E10	DMC0_VREF	J02	PC_06	M13	DMC0_LDM
B01	DMC0_A07	E12	SYS_BMODE0	J03	SYS_RESOUT	M14	SYS_CLKIN
B02	DMC0_A08	E13	DMC0_DQ08	J04	VDD_INT	N01	RTC0_XTAL
B03	DMC0_A11	E14	DMC0_DQ07	J05	VDD_RTC	N02	PB_14
B04	DMC0_A10	F01	DMC0_A01	J06	GND	N03	PB_11
B05	DMC0_A12	F02	DMC0_A02	J07	GND	N04	PC_14
B06	DMC0_WE	F03	PC_09	J08	GND	N05	PC_11
B07	DMC0_CS0	F04	VDD_INT	J09	GND	N06	USB0_ID
B08	DMC0_ODT	F05	VDD_INT	J10	GND_HADC	N07	USB0_DP
B09	DMC0_CKE	F06	GND	J11	VDD_OTP	N08	PB_08
B10	DMC0_DQ00	F07	GND	J12	PA_13	N09	PB_06
B11	DMC0_DQ02	F08	GND	J13	DMC0_DQ13	N10	PB_00
B12	DMC0_DQ01	F09	GND	J14	DMC0_UDQS	N11	HADC0_VIN2
B13	DMC0_DQ04	F10	VDD_DMC	K01	PC_04	N12	HADC0_VIN1
B14	DMC0_DQ03	F11	VDD_DMC	K02	PC_01	N13	PA_15
C01	JTG_TDO_SWO	F12	SYS_FAULT	K03	PC_02	N14	SYS_XTAL
C02	JTG_TMS_SWDIO	F13	DMC0_DQ10	K05	VDD_EXT	P01	GND
C03	JTG_TCK_SWCLK	F14	DMC0_DQ09	K06	VDD_EXT	P02	PB_13
C04	PA_01	G01	DMC0_A03	K07	VDD_EXT	P03	PB_10
C05	SYS_EXTWAKE	G02	PA_00	K08	VDD_EXT	P04	PC_13
C06	PA_02	G03	PC_08	K09	VDD_EXT	P05	USB0_XTAL
C07	SYS_NMI	G04	VDD_INT	K10	VDD_HADC	P06	USB0_CLKIN
C08	GND	G05	GND	K12	PA_12	P07	USB0_DM
C09	PA_04	G06	GND	K13	DMC0_DQ15	P08	PB_07
C10	PA_05	G07	GND	K14	DMC0_DQ14	P09	HADC0_VREFN
C11	PA_06	G08	GND	L01	PC_03	P10	HADC0_VREFP
C12	PA_07	G09	GND	L02	TWI0_SDA	P11	HADC0_VIN3
C13	SYS_HWRST	G10	GND	L03	TWI0_SCL	P12	HADC0_VIN0
C14	SYS_BMODE1	G11	VDD_DMC	L06	VDD_USB	P13	PA_14
D01	DMC0_A00	G12	PA_09	L07	VDD_EXT	P14	GND
D02	DMC0_A04	G13	DMC0_DQ11	L08	VDD_EXT		
D03	JTG_TRST	G14	DMC0_DQ12	L09	VDD_EXT		
D06	VDD_DMC	H01	PC_07	L12	PB_02		
D07	VDD_DMC	H02	PC_10	L13	DMC0_UDM		

Table 68. ADSP-BF70x 184-Ball CSP_BGA Ball Assignments (Alphabetical by Signal Name)

Signal Name	Ball No.	Signal Name	Ball No.	Signal Name	Ball No.	Signal Name	Ball No.
DMC0_A00	D01	DMC0_WE	B06	PA_08	D12	SYS_HWRST	C13
DMC0_A01	F01	GND	C08	PA_09	G12	SYS_NMI	C07
DMC0_A02	F02	GND	A01	PA_10	H12	SYS_RESOUT	J03
DMC0_A03	G01	GND	A14	PA_11	H13	SYS_XTAL	N14
DMC0_A04	D02	GND	F06	PA_12	K12	TWI0_SCL	L03
DMC0_A05	E02	GND	F07	PA_13	J12	TWI0_SDA	L02
DMC0_A06	E01	GND	F08	PA_14	P13	USB0_CLKIN	P06
DMC0_A07	B01	GND	F09	PA_15	N13	USB0_DM	P07
DMC0_A08	B02	GND	G05	PB_00	N10	USB0_DP	N07
DMC0_A09	A02	GND	G06	PB_01	M11	USB0_ID	N06
DMC0_A10	B04	GND	G07	PB_02	L12	USB0_VBC	M07
DMC0_A11	B03	GND	G08	PB_03	M12	USB0_VBUS	M06
DMC0_A12	B05	GND	G09	PB_04	M10	USB0_XTAL	P05
DMC0_A13	A08	GND	G10	PB_05	M09	VDD_DMC	D06
DMC0_BA0	A03	GND	H05	PB_06	N09	VDD_DMC	D07
DMC0_BA1	A04	GND	H06	PB_07	P08	VDD_DMC	D08
DMC0_BA2	A05	GND	H07	PB_08	N08	VDD_DMC	D09
DMC0_CAS	A06	GND	H08	PB_09	M08	VDD_DMC	E06
DMC0_CK	A10	GND	H09	PB_10	P03	VDD_DMC	E07
DMC0_CKE	B09	GND	H10	PB_11	N03	VDD_DMC	E08
DMC0_CK	A11	GND	J06	PB_12	M04	VDD_DMC	E09
DMC0_CS0	B07	GND	J07	PB_13	P02	VDD_DMC	F10
DMC0_DQ00	B10	GND	J08	PB_14	N02	VDD_DMC	F11
DMC0_DQ01	B12	GND	J09	PB_15	M03	VDD_DMC	G11
DMC0_DQ02	B11	GND	L14	PC_00	M01	VDD_DMC	H11
DMC0_DQ03	B14	GND	P01	PC_01	K02	VDD_EXT	K05
DMC0_DQ04	B13	GND	P14	PC_02	K03	VDD_EXT	K06
DMC0_DQ05	D14	GND_HADC	J10	PC_03	L01	VDD_EXT	K07
DMC0_DQ06	D13	HADC0_VIN0	P12	PC_04	K01	VDD_EXT	K08
DMC0_DQ07	E14	HADC0_VIN1	N12	PC_05	J01	VDD_EXT	K09
DMC0_DQ08	E13	HADC0_VIN2	N11	PC_06	J02	VDD_EXT	L07
DMC0_DQ09	F14	HADC0_VIN3	P11	PC_07	H01	VDD_EXT	L08
DMC0_DQ10	F13	HADC0_VREFN	P09	PC_08	G03	VDD_EXT	L09
DMC0_DQ11	G13	HADC0_VREFP	P10	PC_09	F03	VDD_HADC	K10
DMC0_DQ12	G14	JTG_TCK_SWCLK	C03	PC_10	H02	VDD_INT	E05
DMC0_DQ13	J13	JTG_TDI	E03	PC_11	N05	VDD_INT	F04
DMC0_DQ14	K14	JTG_TDO_SWO	C01	PC_12	M05	VDD_INT	F05
DMC0_DQ15	K13	JTG_TMS_SWDIO	C02	PC_13	P04	VDD_INT	G04
DMC0_LDM	M13	JTG_TRST	D03	PC_14	N04	VDD_INT	H04
DMC0_LDQS	A12	PA_00	G02	RTC0_CLKIN	M02	VDD_INT	J04
DMC0_LDQS	A13	PA_01	C04	RTC0_XTAL	N01	VDD_OTP	J11
DMC0_ODT	B08	PA_02	C06	SYS_BMODE0	E12	VDD_RTC	J05
DMC0_RAS	A07	PA_03	A09	SYS_BMODE1	C14	VDD_USB	L06
DMC0_UDM	L13	PA_04	C09	SYS_CLKIN	M14		
DMC0_UDQS	J14	PA_05	C10	SYS_CLKOUT	H03		
DMC0_UDQS	H14	PA_06	C11	SYS_EXTWAKE	C05		
DMC0_VREF	E10	PA_07	C12	SYS_FAULT	F12		